

6. Assembly Information and Production Guidance

6.1 Production Guidance (Important)

- The stamp hole package module produced by Mxchip must completely being patched by SMT machine in 24 hours after open firmware package. Otherwise the module should be re-package by vacuum pumping and drying before patch.

- Devices for SMT patch:

- (1) Reflow soldering machine
- (2) AOI detector
- (3) Suction nozzle with 6-8mm caliber

- Device for drying:

- (1) Cabinet type oven
- (2) Anti-static and high thermos tolerant tray
- (3) Anti-static and high thermos tolerant gloves

- Conditions of product storage (Storage environment is shown in figure 8):